

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 (currently amended). A solder paste printing method comprising:

a first process for mounting a mask having apertures corresponding to land portions of a printed circuit board, on said printed circuit board at a predetermined position thereof in a state where it is placed in position;

a second process for mounting a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder on said mask and for permitting said solder paste to make rolling from one end of said mask toward the opposite end thereof by means of a squeegee, while maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value, wherein said ~~squeegee urges~~ squeegee urges said solder paste to make rolling, to thereby fill said solder paste into said apertures; and

a third process for separating said mask away from said printed circuit board.

2 (original). The solder paste printing method according to claim 1, wherein said moisture is equal to or less than 10 g/m^3 .

3 (original). The solder paste printing method according to claim 2, wherein said atmosphere mainly comprises a nitrogen gas (N_2).

4 (original). A solder paste printing apparatus comprising:

a mask having apertures corresponding to land portions of a printed circuit board;

a squeegee urging a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder and mounted on said mask, which is placed in position at a predetermined position on said printed circuit board to make rolling from one end of said mask toward the opposite end thereof; and

a moisture regulating means for maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value.

5 (currently amended). The solder paste printing apparatus according to claim 4, wherein said moisture regulating means is designed to regulate moisture to a degree equal to or less than 10 g/m³.

6 (currently amended). The solder paste printing apparatus according to claim 5, wherein said atmosphere mainly comprises a nitrogen gas (N₂) supplied by a gas source.